

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4167308

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KEVIN BILLS	11/26/2016
MAHESH BOHRA	11/14/2016
JINWOO CHOI	11/14/2016
TAE HONG KIM	11/17/2016
ROHAN MANDREKAR	11/14/2016
RECEIVING PARTY DATA	
Name:	INTERNATIONAL BUSINESS MACHINES CORPORATION
Street Address:	NEW ORCHARD ROAD
City:	ARMONK
State/Country:	NEW YORK
Postal Code:	10504
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14613893
CORRESPONDENCE DATA	
Fax Number:	(404)607-9981
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	4046079991
Email:	usptopatentmail@cantorcolburn.com
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Address Line 1:	20 CHURCH STREET, 22ND FLOOR
Address Line 4:	HARTFORD, CONNECTICUT 06103-3207
ATTORNEY DOCKET NUMBER:	AUS920090132US4
NAME OF SUBMITTER:	JEFFREY L. WATERS
SIGNATURE:	/jeffreylwaters53749/
DATE SIGNED:	12/02/2016
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 10	

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**DECLARATION (37 C.F.R. 1.63) FOR UTILITY PATENT APPLICATION USING AN
APPLICATION DATA SHEET (37 C.F.R. 1.76) AND ASSIGNMENT**

Title of Invention: **CORELESS MULTI-LAYER CIRCUIT SUBSTRATE WITH MINIMIZED
PAD CAPACITANCE**

As a below named and undersigned inventor, I hereby declare that:

This declaration is directed to the attached application, or (if following box is checked):

United States application or PCT international application number 14/613,893 filed on
February 4, 2015.

The above-identified application was made or authorized to be made by me.

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I have reviewed and understand the contents of the application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR Section 1.56.

Whereas, I ("ASSIGNOR") have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") disclosed in the above-identified patent application and further identified by the IBM Docket Number provided above in the header of this document;


Whereas, International Business Machines Corporation (herein referred to as the "ASSIGNEE"), a corporation of New York having a place of business at Armonk, New York, desires to acquire, and I desire to grant to the ASSIGNEE, my entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, I hereby sell or have sold, assign or have assigned, and otherwise transfer or have transferred to the ASSIGNEE, its successors, legal representatives, and assigns, my entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, I hereby authorize and request the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to the ASSIGNEE, its successors, legal representatives, and assigns, my entire worldwide right, title, and interest in and to the same to be held and enjoyed by the ASSIGNEE, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by me had this Assignment not been made; and I agree to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in the ASSIGNEE, its successors, legal representatives, and assigns, whenever requested by the ASSIGNEE, its successors, legal representatives, or assigns.

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I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

(1) Legal Name of Inventor: **KEVIN BILLS**

Signature:  Date: 11/26/16

(2) Legal Name of Inventor: **MAHESH BOHRA**

Signature: _____ Date: _____

(3) Legal Name of Inventor: **JINWOO CHOI**

Signature: _____ Date: _____

(4) Legal Name of Inventor: **TAE HONG KIM**

Signature: _____ Date: _____

(5) Legal Name of Inventor: **ROHAN MANDREKAR**

Signature: _____ Date: _____

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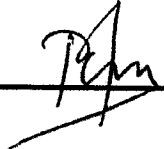
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Signature: _____ Date: _____

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Signature:  _____ Date: 11/14/2016

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Signature: _____ Date: _____

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Signature: _____ Date: _____

(3) Legal Name of Inventor: **JINWOO CHOI**

Signature: Choi jinwoo Date: 11/14/2016

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Signature: _____ Date: _____

(4) Legal Name of Inventor: **TAE HONG KIM**

Signature: Tae Hong Kim Date: 11/17/2016

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Signature: _____ Date: _____

(2) Legal Name of Inventor: **MAHESH BOHRA**

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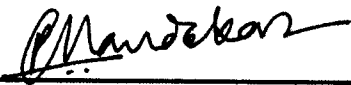
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